Listing of Claims:

Claim 1 (currently amended): A composite heat sink device for surface mounting to a circuit board, said device comprising:

a heat sink body consisting essentially of aluminum, said body comprising at least ~~one~~ two mounting ~~land~~ lands with ~~a~~ respective substantially planar ~~surface~~ bottom surfaces which are coplanar to each other, and

~~a~~ at least two discrete thermally conductive solderable ~~element~~ elements mechanically fixed to ~~each~~ respective said mounting ~~land~~ lands, each said element having a first planar surface which is contiguous with ~~at least one~~ a respective said planar bottom surface of said heat sink body and an opposed second planar surface for soldering to said circuit board, said first and second planar surfaces being substantially parallel.

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Claim 2 (cancelled)

Claim 3 (currently amended): A composite heat sink device as in claim ~~2~~ 1 wherein said body comprises a heat dissipating fin upstanding from each of said lands, and a bight ~~upstanding from~~ connecting said ~~lands~~ fins between said ~~fins~~ lands.

Claim 4 (original): A composite heat sink device as in claim 3 wherein said bight has a planar section which is parallel to said lands and intended to be arranged over an electronic device on said circuit board.

Claim 5 (original): A composite heat sink device as in claim 1 wherein said heat sink body is formed from a sheet of aluminum.

Claim 6 (original): A composite heat sink device as in claim 5 wherein said heat sink body is formed from a sheet of anodized aluminum.

Claim 7 (original): A composite heat sink device as in claim 6 wherein said anodized aluminum is blackened.

Claim 8 (original): A composite heat sink device as in claim 1 wherein said heat sink body is extruded.

Claim 9 (currently amended): A composite heat sink device as in claim 1 wherein each said element is mechanically fixed to a respective said land by providing at least one projection on each said land, providing at least one socket in each said element, and inserting each said projection into a respective ~~at least one~~ said socket in an interference fit.

Claim 10 (original): A composite heat sink device as in claim 9 wherein the element is swaged onto the land.